



Attorney Docket No.: 09792909.5338
Customer No.: 26263

#7/a

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L. Spwell

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

Kazutoshi SHIMIZUME

Group Art Unit: 2826

Application No.: 10/073,134

Examiner: Tan N. Tran

Confirmation No.: 6397

Filed: February 11, 2002

For: SEMICONDUCTOR DEVICE CARRYING A PLURALITY OF CIRCUITS

AMENDMENT UNDER 37 C.F.R. § 1.111

Commissioner Of Patents and Trademarks
Washington, D.C. 20231

Sir:

In response to the Non-Final Office Action dated September 24, 2002 Paper No. 5, please amend the above-identified application as follows:

IN THE SPECIFICATION:

Page 1, please replace the fifth paragraph with the following new paragraph:

Each of the input/output pads 22 is typically shaped to have a square with a side of approximately 100 μm . Due to limitations of mechanical accuracy of a bonding apparatus for use in a wire bonding process, it is difficult to significantly reduce the input/output pads 22 in size. Thus, when the required number of input/output pads 22 are arranged in the periphery of the rectangular chip 20 as shown in Fig. 5, the minimum chip size is accordingly determined.

Page 2, please replace the second paragraph with the following new paragraph:

With an increasingly miniaturized LSI, a higher speed processing ability, and realization of an extremely large-scale integrated circuit in a very limited area on a chip, however, the overall active region 21 may not be filled with circuits. In this case, the active region 21 includes a no-patterned region which has no circuit mounted therein. A no-patterned region may also occur for circuits that involve relatively simple signal processing and uses a small number of gates.

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